

ABSTRACT OF THE DISCLOSURE

The invention relates to photoresist composition suitable for use at 10-165 nm comprising: (a) a polymeric binder (b) a photoactive compound (c) a dissolution inhibitor, the dissolution inhibitor comprising at least (i) two aromatic groups, (ii) fluorine and (iii) a blocked acid group which when unblocked has a $pK_a < 12$. Preferred dissolution inhibitors are optionally blocked bisphenol derivatives in which the bridging carbon atom is substituted with a fluorinated aliphatic group.